

Kulicke & Soffa to Exhibit at Europe's Largest Event on System Integration in Microelectronics

SINGAPORE, Apr 24, 2012 (BUSINESS WIRE) --Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("K&S" or the "Company") announced today that it will be exhibiting at the SMT Hybrid Packaging Show, Europe's largest event on system integration in microelectronics. Concurrently, K&S will be a featured speaker as it presents technical research at the PCIM Europe show. Both events will be held in Nuremberg, Germany from May 8 - 10, 2012.

Kulicke & Soffa will be at the SMT Hybrid Packaging Show in booth #7-322, exhibiting the advanced capabilities of the Orthodyne 3600Plus Hybrid, Copper-Capable, Wedge Bonder and the Orthodyne 3700Plus Small Wire Wedge Bonder.

K&S will share its latest developments in copper wire bonding and aluminum-clad ribbon bonding and will exhibit these advanced capabilities at the premier trade show. In addition to increasing the reliability of the top-side interconnect during power cycling; copper's proven advantages over aluminum also include improvements to mechanical strength, current carrying capability and thermal dissipative properties while allowing for higher junction temperatures.

Matt Vorona, Kulicke & Soffa's Vice President for the Wedge Bond Business Unit, said, "SMT & PCIM have always been valuable platforms for us to reach our target customers in Europe and promote our R&D advancements. These are great opportunities to share our insights and to uncover new opportunities given our industry leadership and dedication to developing next generation hardware and processes to address the industry's new materials and interconnect needs."

For the PCIM Europe show, K&S is presenting recently published technical findings during the "Wire Bonds in Power Modules" conference on May 10 at 14:30 CEST. The technical publication titled "Large Cu Wire Wedge Bonding on Wafers with Cu Pad Metallization" was written in collaboration with Atotech Deutschland. People unable to attend the show but interested in receiving a copy of the white paper can download a copy off the K&S website after the show.

SMT Hybrid Packaging is Europe's largest event on system integration in microelectronics. PCIM Europe is Europe's leading meeting point for specialists in power electronics and its applications in intelligent motion and power quality. Visiting PCIM Europe is free of charge for visitors of SMT Hybrid Packaging. Visiting SMT is also free of charge for visitors of PCIM.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding die and wedge bonders and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

SOURCE: Kulicke & Soffa Industries, Inc.

Kulicke & Soffa Industries, Inc.

Sheila Frese

Public Relations

P: +1-949-660-0440

F: +1-949-660-0444

sfrese@kns.com

or

Joseph Elgindy

Investor Relations

P: +1-215-784-7518

F: +1-215-784-6180

jelgindy@kns.com

or

Global IR Partners

David Pasquale

P: +1-914-337-8801

klic@globalirpartners.com

<https://investor.kns.com/2012-04-23-Kulicke-Soffa-to-Exhibit-at-Europes-Largest-Event-on-System-Integration-in-Microelectronics>